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~~16~~ (new). An electronic device package comprising:
 an integrated circuit chip having chip pads on a top surface;
 a flexible layer overlying the integrated circuit chip, the flexible layer having via openings
 extending to the chip pads; and

a pattern of electrical conductors extending over portions of the flexible layer and into the
 via openings and forming a reconfigured universal array of test and interconnection pads on the
 flexible layer,

the integrated circuit chip, the flexible layer, and the pattern of electrical conductors
 forming a known good electronic device package.

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~~17~~ (new). The device in claim ~~16~~ wherein the flexible layer includes at least one
 resistor and wherein the pattern of electrical conductors couples the at least one resistor to at
 least one of the test and interconnection pads.

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~~18~~ (new). The device of claim ~~16~~ wherein the flexible layer comprises a polymer.

REMARKS

Approval of the amendments is respectfully requested.

Respectfully submitted,

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